

Reduction in Majority-Carrier Concentration in Lightly-Doped 4H-SiC Epilayers by Electron Irradiation

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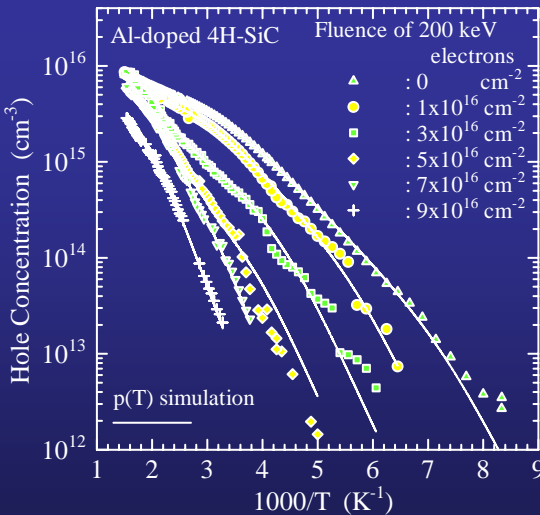
Abstract. The mechanisms for the reduction in the hole concentration in lightly Al-doped p-type 4H-SiC epilayers by electron irradiation as well as in the electron concentration in lightly N-doped n-type 4H-SiC epilayers by electron irradiation are investigated.

In the p-type 4H-SiC epilayers, the temperature dependence of the hole concentration, $p(T)$, is not changed by 100 keV electron irradiation, while the $p(T)$ is decreased by 150 keV electron irradiation. The density of Al acceptors with energy level $E_V+0.22$ eV decreases with increasing fluence of 150 keV electrons, whereas the density of deep acceptors with energy level $E_V+0.38$ eV increases.

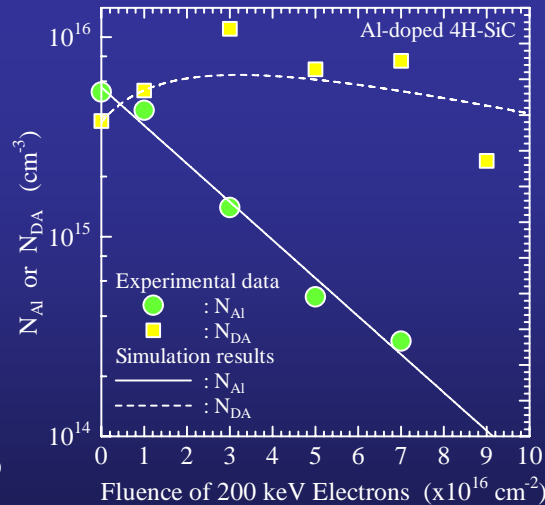
In the n-type 4H-SiC epilayers, the temperature dependence of the electron concentration, $n(T)$, is decreased by 200 keV electron irradiation. The density of N donors located at hexagonal C-sublattice sites decreases significantly with increasing fluence of 200 keV electrons, whereas the density of N donors located at cubic C-sublattice site decreases slightly.

Back Ground of This Study

200 keV electron irradiation



Ref. H. Matsuura et. al: JAP 104 (2008) 043702



Experimental Samples

- 1) 10 μ m-thick Al-doped 4H-SiC
- 2) 10 μ m-thick N-doped 4H-SiC

Electron irradiations

Irradiation at room temperature

Hall-effect measurements

van der Pauw configuration

Magnetic field: 1.4 T

Analysis of temperature dependence of majority-carrier concentration

Free Carrier Concentration Spectroscopy (FCCS)

Results

A) $p(T)$ was unchanged by 100 keV electron irradiation.

Fluence dependence of Al acceptor density

$$\frac{dN_{Al}}{d\Phi} = -\kappa_{Al200} N_{Al}$$

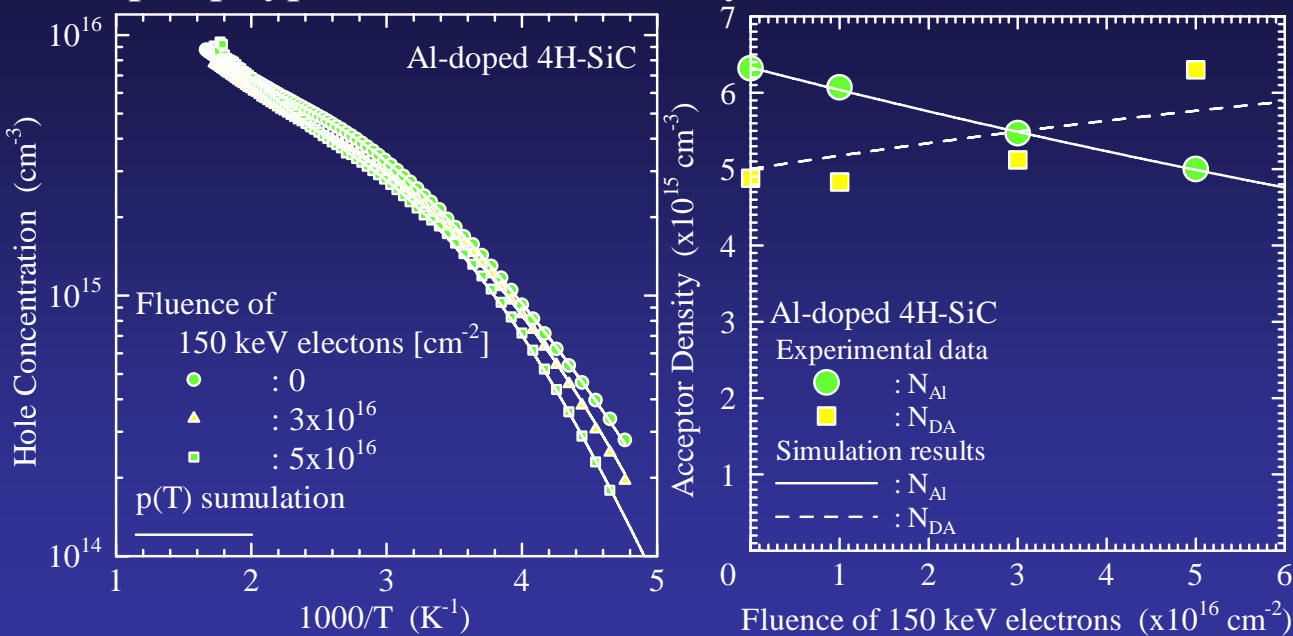
Fluence dependence of deep acceptor density

$$\frac{dN_{DA}}{d\Phi} = -\frac{dN_{Al}}{d\Phi} - \kappa_{DA200} N_{DA}$$

$\kappa_{Al200} = 4.4 \times 10^{-17} \text{ cm}^2$

$\kappa_{DA200} \cong 1 \times 10^{-17} \text{ cm}^2$

Al-doped p-type 4H-SiC irradiated by 150 keV electrons



N_{Al} : Density of Al acceptors

with $E_{\text{V}} + 0.22 \text{ eV}$

$$\frac{dN_{\text{Al}}}{d\Phi} = -\kappa_{\text{Al150}} N_{\text{Al}}$$

$$\kappa_{\text{Al150}} = 4.8 \times 10^{-18} \text{ cm}^2$$

N_{DA} : Density of deep acceptors

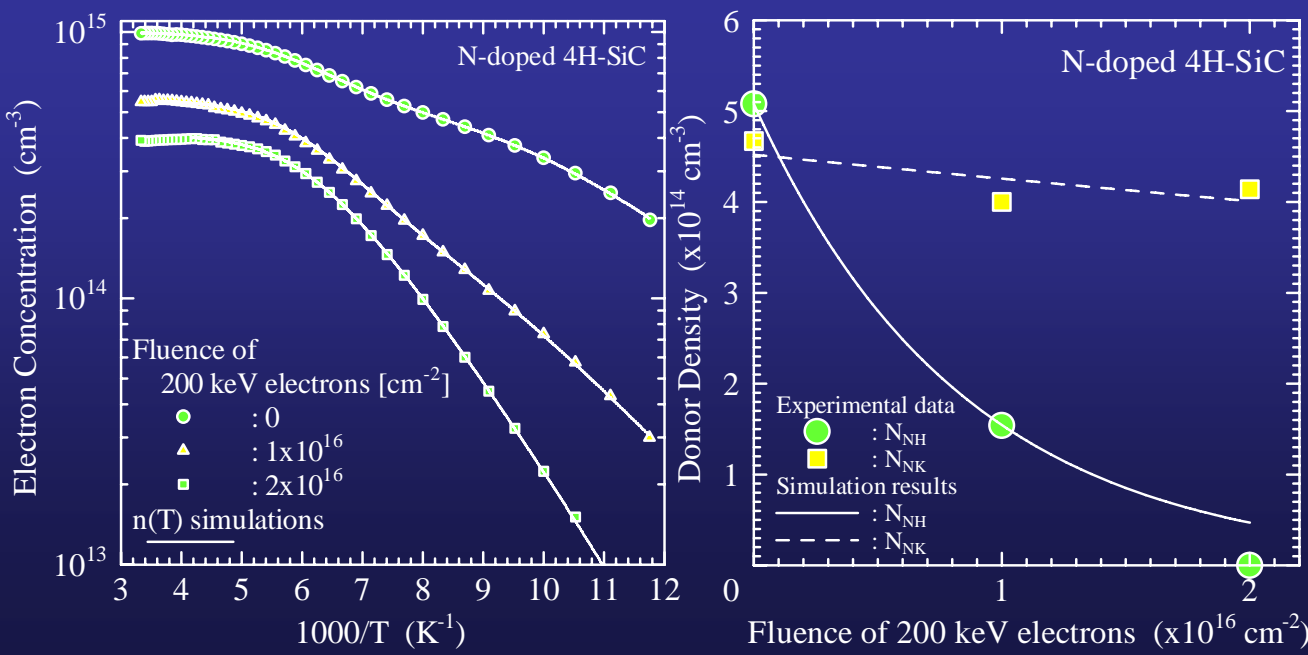
with $E_{\text{V}} + 0.38 \text{ eV}$

$$\frac{dN_{\text{DA}}}{d\Phi} = -\frac{dN_{\text{Al}}}{d\Phi} - \kappa_{\text{DA150}} N_{\text{DA}}$$

$$\kappa_{\text{DA150}} \cong 1 \times 10^{-18} \text{ cm}^2$$

B) 150 keV electron irradiation may transform Al acceptors into deep acceptors.

N-doped n-type 4H-SiC irradiated by 200 keV electrons



N_{NH} : Density of N donors at

hexagonal sites with $E_{\text{C}} - 0.07 \text{ eV}$

$$\frac{dN_{\text{NH}}}{d\Phi} = -\kappa_{\text{NH200}} N_{\text{NH}}$$

$$\kappa_{\text{NH200}} \cong 1.2 \times 10^{-16} \text{ cm}^2$$

N_{NK} : Density of N donors

at cubic sites with $E_{\text{C}} - 0.12 \text{ eV}$

$$\frac{dN_{\text{NK}}}{d\Phi} = -\kappa_{\text{NK200}} N_{\text{NK}}$$

$$\kappa_{\text{NK200}} \cong 6.0 \times 10^{-18} \text{ cm}^2$$

C) N donors at hexagonal sites are less radiation-resistant than N donors at cubic sites.